Title (en)

LEADLESS STACK COMPRISING MULTIPLE COMPONENTS

Title (de)

LEITUNGSLOSER STAPEL MIT MEHREREN KOMPONENTEN

Title (fr)

PILE SANS FIL COMPRENANT DE MULTIPLES COMPOSANTS

Publication

EP 3664958 A4 20210825 (EN)

Application

EP 18844928 A 20180725

Priority

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- US 2018043649 W 20180725

Abstract (en)

[origin: WO2019032294A1] An electronic component is described wherein the electronic component comprises a stack of electronic elements comprising a transient liquid phase sintering adhesive between and in electrical contact with each said first external termination of adjacent electronic elements.

IPC 8 full level

H01G 4/38 (2006.01); **B22F 1/107** (2022.01); **H01G 2/06** (2006.01); **H01G 4/232** (2006.01); **H01G 4/40** (2006.01)

CPC (source: EP US)

B22F 1/107 (2022.01 - EP US); **B22F 7/064** (2013.01 - EP); **B23K 35/262** (2013.01 - EP US); **B32B 37/1207** (2013.01 - EP); **H01G 4/232** (2013.01 - EP); **H01G 4/2325** (2013.01 - EP); **H01G 4/30** (2013.01 - EP); B23K 35/025 (2013.01 - EP); B23K 35/3006 (2013.01 - EP); B23K 35/302 (2013.01 - EP); B23K 35/36 (2013.01 - EP); B23K 35/3613 (2013.01 - EP); B32B 2037/1215 (2013.01 - EP)

Citation (search report)

- [X] US 2017025223 A1 20170126 - BULTITUDE JOHN [US], et al
- [X] WO 2014081666 A1 20140530 - KEMET ELECTRONICS CORP [US]
- [A] US 5038996 A 19910813 - WILCOX JAMES R [US], et al
- [A] US 2016118190 A1 20160428 - PARK HEUNG KIL [KR], et al
- See references of WO 2019032294A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

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DOCDB simple family (application)

US 2018043649 W 20180725; CN 201880051625 A 20180725; EP 18844928 A 20180725; JP 2020506336 A 20180725; JP 2022024677 A 20220221